

IN THE SPECIFICATION:

Please insert the following paragraph on page 1, line 2, before the Field of the Invention.

-- Related Applications:

This application is a Divisional application of Serial No. 09/430,965, filed November 1, 1999, now issued as United States Patent No. 6,347,901. --

Please amend the paragraph beginning on page 8, line 5 as indicated.

Referring to FIGURE 4, a solder joint ~~at the~~ having an intermetallic region formed between solder 25 and the pad 10 and an intermetallic boundary 15 is shown, ~~using.~~ The pad 10 has the serpentine solder configuration depicted in FIGURE 3a. It will be observed that the respective micro-cracking 20 at ~~each~~ intermetallic boundary 15 is following a circuitous or meandering path. The lengthening of the crack pathway increases the useful life of the solder joint. Other pad

configurations are shown in FIGURES 3b through 3d. As before, this results in micro-crack pathways that ~~which~~ are interrupted, lengthened, or constrained. In a similar manner, these configurations are expected to increase fatigue life of the solder joint, as is that of the solder design shown in FIGURE 3a.